



6AU-2841

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applicant: Brad D. Rumsey § Art Unit: 2841
Serial No.: 09/377,286 §
Filed: August 18, 1999 § Examiner: K. Cuneo
Title: Positioning Flowable § Docket No. MICT-0050-US
Solder For Bonding § (99-0325)
Integrated Circuit
Elements §

Commissioner for Patents
Washington, D.C. 20231

6/14/01 A
R. Tyson
6/14/01
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Sir:

6/14/01 ✓
This paper is submitted in response to the Office Action dated March 14, 2001 for which the shortened-statutory period for response is set to expire on June 14, 2001. The Applicant respectfully requests that the Examiner make amendments to the above referenced application as follows:

In the Claims

Please amend claim 1 as follows:

A

1. (Amended) A bond pad assembly comprising:
 2. a bond pad;
 3. a trace that applies an attractive force to solder placed on
 4. the pad, said trace coupled to said pad and extending away from said pad in a
 5. first direction; and

Date of Deposit: *5/21/01*

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class mail** with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, Washington, DC 20231.

Sharon V. Hart
Sharon V. Hart